

Features

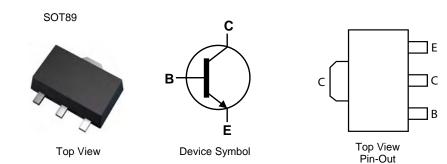
- I_c = 1A Continuous Collector Current
- Low Saturation Voltage V_{CE(sat)} < 500mV @ 0.5A
- Gain groups 10 and 16
- Epitaxial Planar Die Construction
- Complementary PNP types: BCX51, 52 and 53
- Lead-Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Devices (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound (Note 2)
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.072 grams (Approximate)

Applications

- Medium Power Switching or Amplification Applications
- AF driver and output stages



Ordering Information (Note 3)

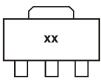
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCX54TA	BA	7	12	1,000
BCX5410TA	BC	7	12	1,000
BCX5416TA	BD	7	12	1,000
BCX55TA	BE	7	12	1,000
BCX5510TA	BG	7	12	1,000
BCX5516TA	BM	7	12	1,000
BCX56TA	BH	7	12	1,000
BCX5610TA	BK	7	12	1,000
BCX5616TA	BL	7	12	1,000
BCX5316TC	BL	13	12	4,000

Notes: 1. No purposefully added lead.

2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

3. For packaging details, go to our website http://www.diodes.com

Marking Information



xx = Product Type Marking Code, as follows:

 BCX54
 = BA
 BCX55
 = BE
 BCX56
 = BH

 BCX5410
 = BC
 BCX5510
 = BG
 BCX5610
 = BK

 BCX5416
 = BD
 BCX5516
 = BM
 BCX5616
 = BL



Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	BCX54	BCX55	BCX56	Unit
Collector-Base Voltage	V _{CBO}	45	60	100	V
Collector-Emitter Voltage	V _{CEO}	45	60	80	V
Emitter-Base Voltage	V _{EBO}	5			V
Continuous Collector Current	lc	1			^
Peak Pulse Collector Current	I _{CM}	1.5			A
Continuous Base Current	IB	100			
Peak Pulse Base Current	I _{BM}	200			mA

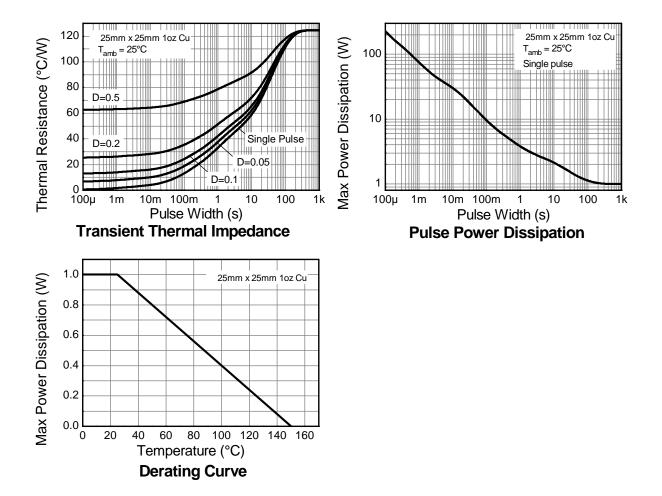
Thermal Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	PD	1	W
Thermal Resistance, Junction to Ambient (Note 4)	R _{0JA}	124	°C/W
Thermal Resistance, Junction to Leads (Note 5)	R _{θJL}	10.0	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-65 to +150	°C

4. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured Notes: when operating in a steady-state condition.
Thermal resistance from junction to solder-point (on the exposed collector pad).



Thermal Characteristics

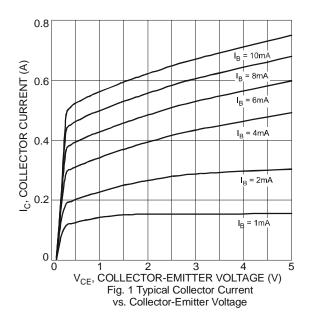


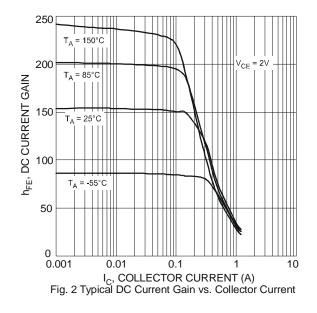


Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Callastar Daga	BCX54	BV _{CBO}	45			V	I _C = 100μΑ
Collector-Base Breakdown Voltage	BCX55		60	-	-		
Dieakuuwii vullage	BCX56		100				
Collector-Emitter	BCX54	BV _{CEO}	45		-	V	I _C = 10mA
Breakdown Voltage (Note 6)	BCX55		60	-			
Dieakuuwii vuitage (Note 6)	BCX56		80				
Emitter-Base Breakdown Voltage		BV _{EBO}	5	-	-	V	I _E = 10μΑ
Collector Cut-off Current		I _{CBO}			0.1 20	μA	$V_{CB} = 30V$
			-	-			V _{CB} = 30V, T _A = 150°C
Emitter Cut-off Current		I _{EBO}	-	-	20	nA	$V_{EB} = 4V$
			25	-	-		$I_{C} = 5mA, V_{CE} = 2V$
	All versions	h _{FE}	40	-	250		$I_{C} = 150 \text{mA}, V_{CE} = 2 \text{V}$
Static Forward Current Transfer			25	-	-		I _C = 500mA, V _{CE} = 2V
Ratio (Note 6)	10 gain grp		63	-	160		$I_{C} = 150 \text{mA}, V_{CE} = 2 \text{V}$
	16 gain grp		100	-	250		$I_{C} = 150 \text{mA}, V_{CE} = 2 \text{V}$
Collector-Emitter Saturation Voltage (Note 6)		V _{CE(sat)}	-	-	0.5	V	$I_{\rm C} = 500$ mA, $I_{\rm B} = 50$ mA
Base-Emitter Turn-On Voltage (Note 6)		V _{BE(on)}	-	-	1.0	V	$I_{C} = 500 \text{mA}, V_{CE} = 2 \text{V}$
Transition Frequency		f⊤	150	-	-	MHz	I _C = 50mA, V _{CE} = 10V f = 100MHz
Output Capacitance		Cobo	-	-	25	pF	V _{CB} = 10V, f = 1MHz

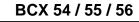
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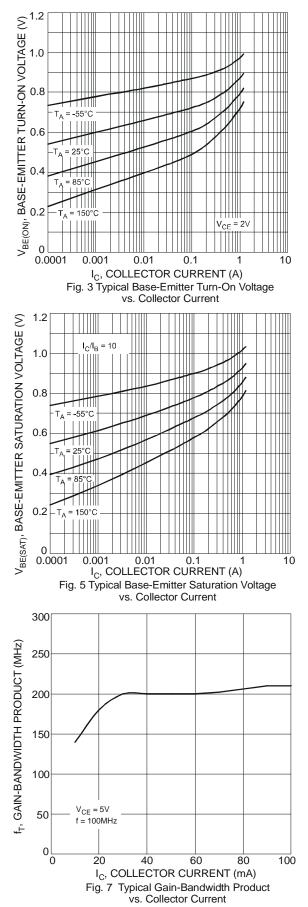
6. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%. Notes:

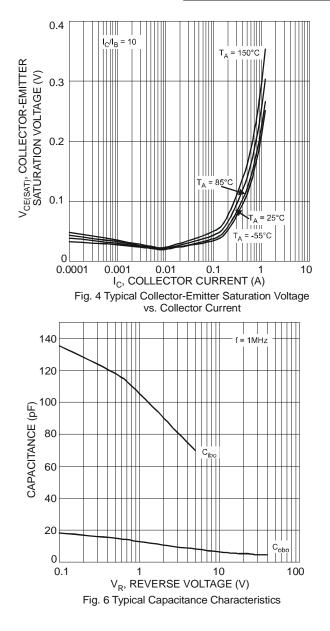






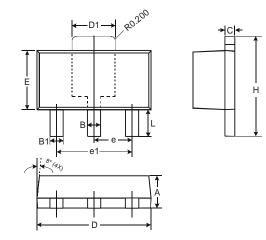






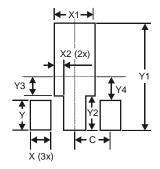


Package Outline Dimensions



SOT89					
Dim	Min	Max			
Α	1.40	1.60			
В	0.44	0.62			
B1	0.35	0.54			
С	0.35	0.43			
D	4.40	4.60			
D1	1.52	1.83			
Е	2.29	2.60			
Е	1.50 Typ				
e1	3.00 Тур				
н	3.94	4.25			
L	0.89	1.20			
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500



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